## **Tyrone Camarero Specifications**

## Camarero DS30012TP-224RN

## **Key features**

## Two hot-pluggable systems (nodes) in a 2U Form Factor. Each node supports the following

- Dual socket R3 (LGA 2011) supports Intel® Xeon® processor E5-2600v4/v3 family ٠
- Intel<sup>®</sup> C612 chipset
- Up to 2TB ECC 3DS LRDIMM , up to DDR4-2400 MHz ; 16x DIMM slots •
- 1x PCI-E 3.0 x16, 1x PCI-E 3.0 x8 slots
- Intel® i350 Dual port GbE LAN .
- Integrated IPMI 2.0 with KVM and Dedicated LAN
- 4x NVMe and 8x 2.5" Hot-swap SAS drives
- LSI 3008 SAS3 controller (8 ports); RAID 0, 1, 10 ٠
- 1600W Redundant Power Supplies Titanium Level (96%)





Processor/Cache		Front Panel	
	al socket R3 (LGA 2011) supports Intel <sup>®</sup> on <sup>®</sup> processor E5-2600v4/v3 family	LED Indicators	Power status LED, HDD activity LED, 2x Network activity LEDs, Universal Information (UID) LED
		Buttons	Power On/Off button, UID button
Chipset		Drive Bays	
Chipset Inte	el® C612 chipset	HDD bays	8x 2.5" Hot-swap SAS HDD Bays, 4x 2.5" Hot-swap Bays support NVMe
System Memory		Power Supply	
	x 288-pin DDR4 DIMM slots, Up to 2TB C 3DS LRDIMM, 512 ECC RDIMM	1600W Redundant Power Supplies Titanium Level (96%)	
Expansion Slots		Cooling System	
PCI-Express 1x P	PCI-E 3.0 x16 slot, 1x PCI-E 3.0 x8 slot	4x 8cm heavy duty PWM fans with optimal fan speed control	
Integrated On-Board		Form Factor	
	3008 SAS3 (12Gbps) controller; ID 0, 1, 10 support	Form Factor	2U Rackmount
	RJ45 Gigabit Ethernet LAN ports, RJ45 Dedicated IPMI LAN port	Width: Height:	17.25"(438mm), 3.47" (88mm), 28.75" (720mm)
dd-on Options		Deptn:	26.75 (730mm)
Optical Drive Nor	one	Email : info@tyronesystems.com For more/current product information, visit www.tyronesystems.com	
ategrated On-Board SAS LSI 3 RAII LAN 2x F 1x F dd-on Options	3008 SAS3 (12Gbps) controller; ID 0, 1, 10 support RJ45 Gigabit Ethernet LAN ports, RJ45 Dedicated IPMI LAN port	Form Factor Form Factor Width: Height: Depth: Email For more/cu	2U Rackmount 17.25"(438mm), 3.47" (88mm), 28.75" (730mm) il : info@tyronesystems.com urrent product information, vi

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